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PATENT APPLICATION
JH

IN THE U.S. PATENT AND TRADEMARK OFFICE

October 5, 1993



Applicant: Iver E. ANDERSON, et al
For: Pb-FREE Sn-Ag-Cu TERNARY EUTECTIC SOLDER
Serial No.: 08/094 854 Group: Unknown
Filed: July 20, 1993 Examiner: Unknown
Atty. Docket
No.: ISU Case 340

The Commissioner of Patents and Trademarks
Washington, D. C. 20231
Attention: Application Processing Division,
Special Processing and Correspondence Branch

Sir:

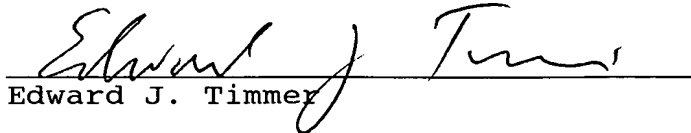
RESPONSE

This is a response to the Patent Office communication mailed
August 4, 1993, a copy of which is enclosed.
(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with
the United States Postal Service as first class mail in an envelope
addressed to: Commissioner of Patents and Trademarks, Washington, D.C.
20231, on October 5, 1993.

Respectfully submitted,


Edward J. Timmer

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